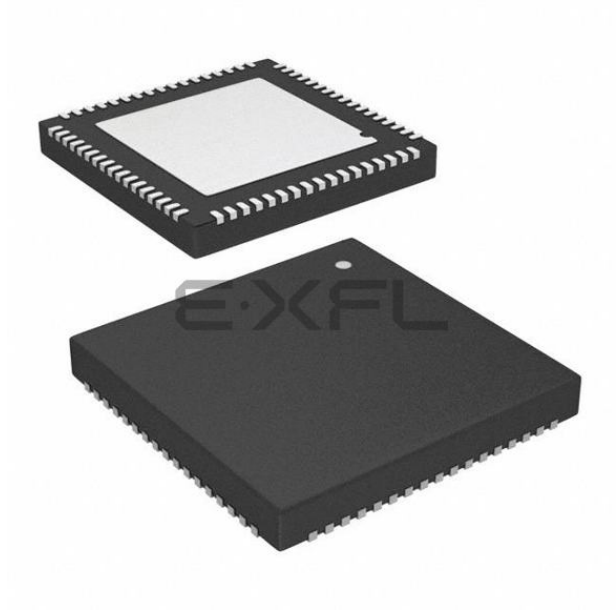


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	67MHz
Connectivity	I²C, LINbus, SPI, UART/USART, USB
Peripherals	CapSense, DMA, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 1x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-VFQFN Exposed Pad
Supplier Device Package	68-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c5368lti-026

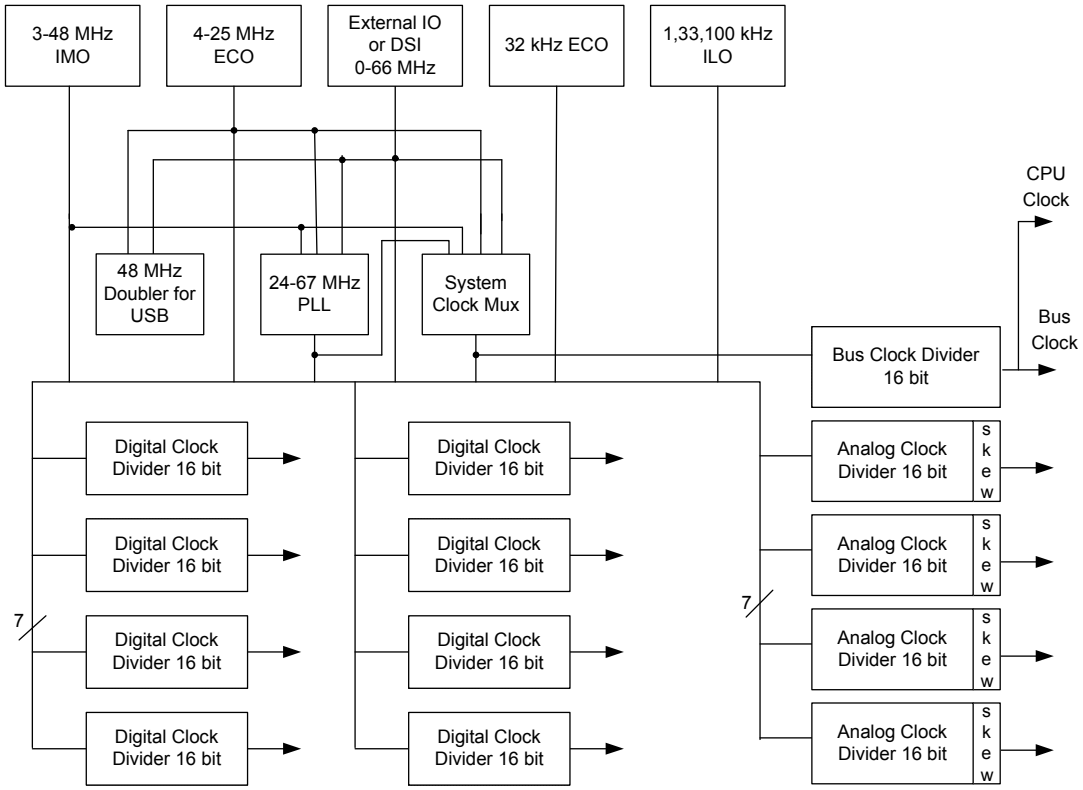
Contents

1. Architectural Overview 3
2. Pinouts 5
3. Pin Descriptions 9
4. CPU 10
4.1 ARM Cortex-M3 CPU 10
4.2 Cache Controller 12
4.3 DMA and PHUB 12
4.4 Interrupt Controller 14
5. Memory 16
5.1 Static RAM 16
5.2 Flash Program Memory 16
5.3 Flash Security 16
5.4 EEPROM 16
5.5 Memory Map 17
6. System Integration 18
6.1 Clocking System 18
6.2 Power System 22
6.3 Reset 24
6.4 I/O System and Routing 25
7. Digital Subsystem 32
7.1 Example Peripherals 32
7.2 Universal Digital Block 36
7.3 UDB Array Description 39
7.4 DSI Routing Interface Description 39
7.5 USB 41
7.6 Timers, Counters, and PWMs 41
7.7 I^2C 43
8. Analog Subsystem 44
8.1 Analog Routing 45
8.2 Successive Approximation ADC 47
8.3 Comparators 47
8.4 Opamps 49
8.5 Programmable SC/CT Blocks 49
8.6 LCD Direct Drive 50
8.7 CapSense 51
8.8 Temp Sensor 51
8.9 DAC 51
8.10 Up/Down Mixer 52
8.11 Sample and Hold 53
9. Programming, Debug Interfaces, Resources 53
9.1 Debug Port Acquisition 54
9.2 SWD Interface 54
9.3 Debug Features 55
9.4 Trace Features 55
9.5 SWV Interface 55
9.6 Programming Features 55
9.7 Device Security 55
10. Development Support 56
10.1 Documentation 56
10.2 Online 56
10.3 Tools 56
11. Electrical Specifications 57
11.1 Absolute Maximum Ratings 57
11.2 Device Level Specifications 58
11.3 Power Regulators 60
11.4 Inputs and Outputs 61
11.5 Analog Peripherals 68
11.6 Digital Peripherals 85
11.7 Memory 88
11.8 PSoC System Resources 90
11.9 Clocking 92
12. Ordering Information 96
12.1 Part Numbering Conventions 97
13. Packaging 98
14. Acronyms 100
15. Reference Documents 101
16. Document Conventions 102
16.1 Units of Measure 102
17. Revision History 103
18. Sales, Solutions, and Legal Information 105

Table 4-6. Interrupt Vector Table

Interrupt #	Cortex-M3 Exception #	Fixed Function	DMA	UDB
0	16	Low voltage detect (LVD)	phub_termout0[0]	udb_intr[0]
1	17	Cache	phub_termout0[1]	udb_intr[1]
2	18	Reserved	phub_termout0[2]	udb_intr[2]
3	19	Pwr Mgr	phub_termout0[3]	udb_intr[3]
4	20	PICU[0]	phub_termout0[4]	udb_intr[4]
5	21	PICU[1]	phub_termout0[5]	udb_intr[5]
6	22	PICU[2]	phub_termout0[6]	udb_intr[6]
7	23	PICU[3]	phub_termout0[7]	udb_intr[7]
8	24	PICU[4]	phub_termout0[8]	udb_intr[8]
9	25	PICU[5]	phub_termout0[9]	udb_intr[9]
10	26	PICU[6]	phub_termout0[10]	udb_intr[10]
11	27	PICU[12]	phub_termout0[11]	udb_intr[11]
12	28	PICU[15]	phub_termout0[12]	udb_intr[12]
13	29	Comparators Combined	phub_termout0[13]	udb_intr[13]
14	30	Switched Caps Combined	phub_termout0[14]	udb_intr[14]
15	31	I^2C	phub_termout0[15]	udb_intr[15]
16	32	Reserved	phub_termout1[0]	udb_intr[16]
17	33	Reserved	phub_termout1[1]	udb_intr[17]
18	34	Reserved	phub_termout1[2]	udb_intr[18]
19	35	Reserved	phub_termout1[3]	udb_intr[19]
20	36	Reserved	phub_termout1[4]	udb_intr[20]
21	37	USB SOF Int	phub_termout1[5]	udb_intr[21]
22	38	USB Arb Int	phub_termout1[6]	udb_intr[22]
23	39	USB Bus Int	phub_termout1[7]	udb_intr[23]
24	40	USB Endpoint[0]	phub_termout1[8]	udb_intr[24]
25	41	USB Endpoint Data	phub_termout1[9]	udb_intr[25]
26	42	Reserved	phub_termout1[10]	udb_intr[26]
27	43	Reserved	phub_termout1[11]	udb_intr[27]
28	44	Reserved	phub_termout1[12]	udb_intr[28]
29	45	Decimator Int	phub_termout1[13]	udb_intr[29]
30	46	phub_err_int	phub_termout1[14]	udb_intr[30]
31	47	eeprom_fault_int	phub_termout1[15]	udb_intr[31]

Figure 6-1. Clocking Subsystem



6.1.1 Internal Oscillators

6.1.1.1 Internal Main Oscillator

The IMO operates with no external components and outputs a stable clock. A factory trim for each frequency range is stored in the device. With the factory trim, tolerance varies from ±5% at 3 MHz, up to ±10% at 48 MHz. The IMO, in conjunction with the PLL, allows generation of CPU and system clocks up to the device's maximum frequency. The IMO provides clock outputs at 3, 6, 12, 24, and 48 MHz.

6.1.1.2 Clock Doubler

The clock doubler outputs a clock at twice the frequency of the input clock. The doubler works at input frequency of 24 MHz, providing 48 MHz for the USB. It can be configured to use a clock from the MHzECO or the DSI (external pin). The doubler is typically used to clock the USB.

6.1.1.3 Phase-Locked Loop

The PLL allows low frequency, high accuracy clocks to be multiplied to higher frequencies. This is a tradeoff between higher clock frequency and accuracy and, higher power consumption and increased startup time.

The PLL block provides a mechanism for generating clock frequencies based upon a variety of input sources. The PLL outputs clock frequencies in the range of 24 to 67 MHz. Its input and feedback dividers supply 4032 discrete ratios to create almost any desired system clock frequency. The accuracy of the PLL output depends on the accuracy of the PLL input source. The most common PLL use is to multiply the IMO clock at 3 MHz, where it is most accurate, to generate the CPU and system clocks up to the device's maximum frequency.

The PLL achieves phase lock within 250 µs (verified by bit setting). It can be configured to use a clock from the IMO, MHzECO, or DSI (external pin). The PLL clock source can be used until lock is complete and signaled with a lock bit. The lock signal can be routed through the DSI to generate an interrupt. Disable the PLL before entering low power modes.

6.1.1.4 Internal Low Speed Oscillator

The ILO provides clock frequencies for low power consumption, including the sleep timer. The ILO generates up to three different clocks: 1 kHz, 33 kHz, and 100 kHz.

The 1 kHz clock (CLK1K) is typically used for a background 'heartbeat' timer. This clock inherently lends itself to long sleep intervals using the central timewheel (CTW). The central timewheel is a free running counter clocked by the ILO 1 kHz output. The central timewheel is always enabled except in hibernate mode and when the CPU is stopped during debug on chip mode. It can be used to generate periodic interrupts for timing purposes or to wake the system from a low power mode. Firmware can reset the central timewheel.

The central timewheel can be programmed to wake the system periodically and optionally issue an interrupt. This enables flexible, periodic wakeups from low power modes or coarse timing applications. Systems that require accurate timing should use the RTC capability instead of the central timewheel. The 100 kHz clock (CLK100K) works as a low-power system clock to

The term **system reset** indicates that the processor as well as analog and digital peripherals and registers are reset.

A reset status register shows some of the resets or power voltage monitoring interrupts. The program may examine this register to detect and report certain exception conditions. This register is cleared after a power-on reset. For details see the Technical Reference Manual.

6.3.1 Power Voltage Level Monitors

- IPOR - Initial Power on Reset

  At initial power on, IPOR monitors the power voltages V_{DDD} and V_{DDA}, both directly at the pins and at the outputs of the corresponding internal regulators. The trip level is not precise. It is set to approximately 1 volt, which is below the lowest specified operating voltage but high enough for the internal circuits to be reset and to hold their reset state. The monitor generates a reset pulse that is at least 100 ns wide. It may be much wider if one or more of the voltages ramps up slowly.

  To save power the IPOR circuit is disabled when the internal digital supply is stable. When the voltage is high enough, the IMO starts.

- ALVI, DLVI, AHVI - Analog/Digital Low Voltage Interrupt, Analog High Voltage Interrupt

  Interrupt circuits are available to detect when V_{DDA} and V_{DDD} go outside a voltage range. For AHVI, V_{DDA} is compared to a fixed trip level. For ALVI and DLVI, V_{DDA} and V_{DDD} are compared to trip levels that are programmable, as listed in Table 6-4.

Table 6-4. Analog/Digital Low Voltage Interrupt, Analog High Voltage Interrupt

Interrupt	Supply	Normal Voltage Range	Available Trip Settings
DLVI	V_{DDD}	2.7 V-5.5 V	2.45 V-5.45 V in 250 mV increments. The 2.45 V setting is used for LVD.
ALVI	V_{DDA}	2.7 V-5.5 V	2.45 V-5.45 V in 250 mV increments. The 2.45 V setting is used for LVD
AHVI	V_{DDA}	2.7 V-5.5 V	5.75 V

The monitors are disabled until after IPOR. The monitors are not available in low-power modes. To monitor voltages in sleep mode, wake up periodically using the CTW. After wakeup, the 2.45 V LVI interrupt may trigger. Voltage monitoring is not available in hibernate mode.

6.3.2 Other Reset Sources

- XRES - External Reset

  CY8C53 has a dedicated XRES pin which, holds the part in reset while held active (low). The response to an XRES is the same as to an IPOR reset.

  The external reset is active low. It includes an internal pull-up resistor. XRES is active during sleep and hibernate modes.

- SRES - Software Reset

  A reset can be commanded under program control by setting a bit in the software reset register. This is done either directly by the program or indirectly by DMA access. The response to a SRES is the same as after an IPOR reset.

  Another register bit exists to disable this function.

- WRES - Watchdog Timer Reset

  The watchdog reset detects when the software program is no longer being executed correctly. To indicate to the watchdog timer that it is running correctly, the program must periodically reset the timer. If the timer is not reset before a user-specified amount of time, then a reset is generated.

  Note IPOR disables the watchdog function. The program must enable the watchdog function at an appropriate point in the code by setting a register bit. When this bit is set, it cannot be cleared again except by an IPOR power on reset event. The watchdog timer can be used only when the part remains in active mode.

6.4 I/O System and Routing

PSoC I/Os are extremely flexible. Every GPIO has analog and digital I/O capability. All I/Os have a large number of drive modes, which are set at POR. PSoC also provides up to four individual I/O voltage domains through the V_{DDIO} pins.

There are two types of I/O pins on every device; those with USB provide a third type. Both General Purpose I/O (GPIO) and Special I/O (SIO) provide similar digital functionality. The primary differences are their analog capability and drive strength. Devices that include USB also provide two USBIO pins that support specific USB functionality as well as limited GPIO capability.

All I/O pins are available for use as digital inputs and outputs for both the CPU and digital peripherals. In addition, all I/O pins can generate an interrupt. The flexible and advanced capabilities of the PSoC I/O, combined with any signal to any pin routability, greatly simplify circuit design and board layout. All GPIO pins can be used for analog input, CapSense[6], and LCD segment drive, while SIO pins are used for voltages in excess of V_{DDA} and for programmable output voltages.

- Features supported by both GPIO and SIO:
  - Separate I/O supplies and voltages for up to four groups of I/O
  - Digital peripherals use DSI to connect the pins
  - Input or output or both for CPU and DMA
  - Eight drive modes
  - Every pin can be an interrupt source configured as rising edge, falling edge or both edges. If required, level sensitive interrupts are supported through the DSI
  - Dedicated port interrupt vector for each port
  - Slew rate controlled digital output drive mode
  - Access port control and configuration registers on either port basis or pin basis
  - Separate port read (PS) and write (DR) data registers to avoid

6.4.1 Drive Modes

Each GPIO and SIO pin is individually configurable into one of the eight drive modes listed in Table 6-5. Three configuration bits are used for each pin (DM[2:0]) and set in the PRTxDM[2:0] registers. Figure 6-10 depicts a simplified pin view based on each of the eight drive modes. Table 6-5 shows the I/O pin's drive state based on the port data register value or digital array signal if bypass mode is selected. Note that the actual I/O pin voltage is determined by a combination of the selected drive mode and the load at the pin. For example, if a GPIO pin is configured for resistive pull-up mode and driven high while the pin is floating, the voltage measured at the pin is a high logic state. If the same GPIO pin is externally tied to ground then the voltage unmeasured at the pin is a low logic state.

Figure 6-10. Drive Mode

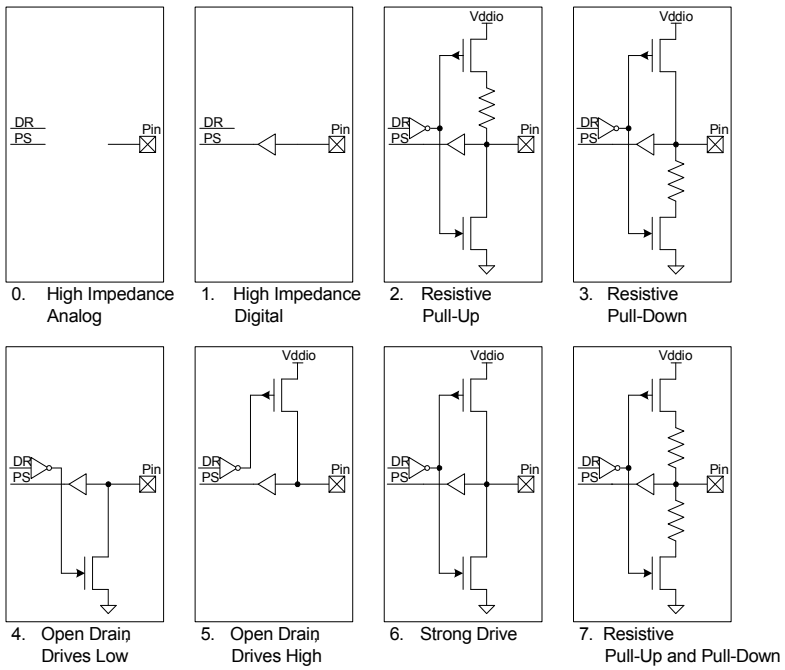


Table 6-5. Drive Modes

Diagram	Drive Mode	PRTxDM2	PRTxDM1	PRTxDM0	PRTxDR = 1	PRTxDR = 0
0	High impedence analog	0	0	0	High-Z	High-Z
1	High Impedance digital	0	0	1	High-Z	High-Z
2	Resistive pull-up[11]	0	1	0	Res High (5K)	Strong Low
3	Resistive pull-down[11]	0	1	1	Strong High	Res Low (5K)
4	Open drain, drives low	1	0	0	High-Z	Strong Low
5	Open drain, drive high	1	0	1	Strong High	High-Z
6	Strong drive	1	1	0	Strong High	Strong Low
7	Resistive pull-up and pull-down[11]	1	1	1	Res High (5K)	Res Low (5K)

- High Impedance Analog

  The default reset state with both the output driver and digital input buffer turned off. This prevents any current from flowing in the I/O's digital input buffer due to a floating voltage. This state is recommended for pins that are floating or that support an analog voltage. High impedance analog pins do not provide digital input functionality.

  To achieve the lowest chip current in sleep modes, all I/Os must either be configured to the high impedance analog mode, or have their pins driven to a power supply rail by the PSoC device or by external circuitry.

- High Impedance Digital

  The input buffer is enabled for digital signal input. This is the standard high impedance (HiZ) state recommended for digital inputs.

Note
11. Resistive pull-up and pull-down are not available with SIO in regulated output mode.

7.1.1 Example Digital Components

The following is a sample of the digital components available in PSoC Creator for the CY8C53 family. The exact amount of hardware resources (UDBs, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- Communications
  - I^2C (1 to 3 UDBs)
  - UART (1 to 3 UDBs)
- Functions
  - PWM (1 to 2 UDBs)
- Logic (x CPLD product terms per logic function)
  - NOT
  - OR
  - XOR
  - AND

7.1.2 Example Analog Components

The following is a sample of the analog components available in PSoC Creator for the CY8C53 family. The exact amount of hardware resources (SC/CT blocks, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- Amplifiers
  - TIA
  - PGA
  - opamp
- ADC
  - Successive Approximation (SAR)
- DACs
  - Current
  - Voltage
  - PWM
- Comparators
- Mixers

7.1.3 Example System Function Components

The following is a sample of the system function components available in PSoC Creator for the CY8C53 family. The exact amount of hardware resources (UDBs, SC/CT blocks, routing, RAM, flash) used by a component varies with the features selected in PSoC Creator for the component.

- CapSense
- LCD Drive
- LCD Control
- Filters

7.1.4 Designing with PSoC Creator

7.1.4.1 More Than a Typical IDE

A successful design tool allows for the rapid development and deployment of both simple and complex designs. It reduces or eliminates any learning curve. It makes the integration of a new design into the production stream straightforward.

PSoC Creator is that design tool.

PSoC Creator is a full featured Integrated Development Environment (IDE) for hardware and software design. It is optimized specifically for PSoC devices and combines a modern, powerful software development platform with a sophisticated graphical design tool. This unique combination of tools makes PSoC Creator the most flexible embedded design platform available.

Graphical design entry simplifies the task of configuring a particular part. You can select the required functionality from an extensive catalog of components and place it in your design. All components are parameterized and have an editor dialog that allows you to tailor functionality to your needs.

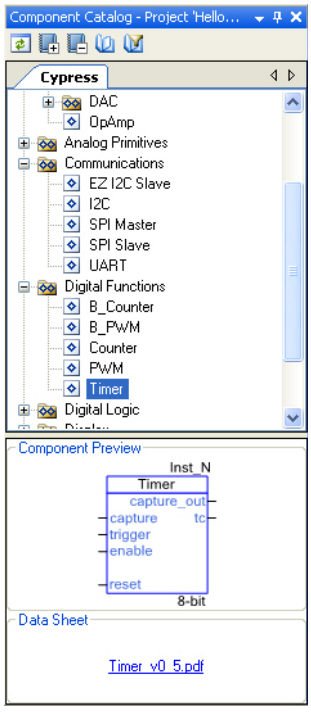
PSoC Creator automatically configures clocks and routes the I/O to the selected pins and then generates APIs to give the application complete control over the hardware. Changing the PSoC device configuration is as simple as adding a new component, setting its parameters, and rebuilding the project.

At any stage of development you are free to change the hardware configuration and even the target processor. To retarget your application (hardware and software) to new devices, even from 8- to 32-bit families, just select the new device and rebuild.

You also have the ability to change the C compiler and evaluate an alternative. Components are designed for portability and are validated against all devices, from all families, and against all supported tool chains. Switching compilers is as easy as editing from the project options and rebuilding the application with no errors from the generated APIs or boot code.

7.1.4.2 Component Catalog

Figure 7-3. Component Catalog



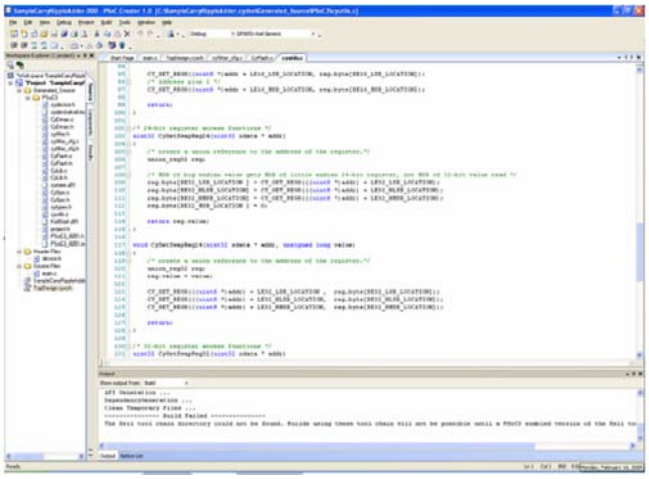
The component catalog is a repository of reusable design elements that select device functionality and customize your PSoC device. It is populated with an impressive selection of content; from simple primitives such as logic gates and device registers, through the digital timers, counters and PWMs, plus analog components such as ADC, DACs, and filters, and communication protocols, such as I^2C and USB. See "Example Peripherals" section on page 32 for more details about available peripherals. All content is fully characterized and carefully documented in data sheets with code examples, AC/DC specifications, and user code ready APIs.

7.1.4.3 Design Reuse

The symbol editor gives you the ability to develop reusable components that can significantly reduce future design time. Just draw a symbol and associate that symbol with your proven design. PSoC Creator allows for the placement of the new symbol anywhere in the component catalog along with the content provided by Cypress. You can then reuse your content as many times as you want, and in any number of projects, without ever having to revisit the details of the implementation.

7.1.4.4 Software Development

Figure 7-4. Code Editor

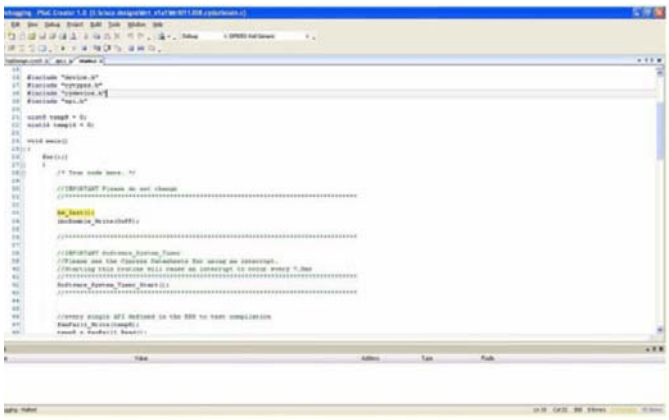


Anchoring the tool is a modern, highly customizable user interface. It includes project management and integrated editors for C and assembler source code, as well the design entry tools.

Project build control leverages compiler technology from top commercial vendors such as ARM® Limited, Keil™, and CodeSourcery (GNU). Free versions of Keil C51 and GNU C Compiler (GCC) for ARM, with no restrictions on code size or end product distribution, are included with the tool distribution. Upgrading to more optimizing compilers is a snap with support for the professional Keil C51 product and ARM RealView™ compiler.

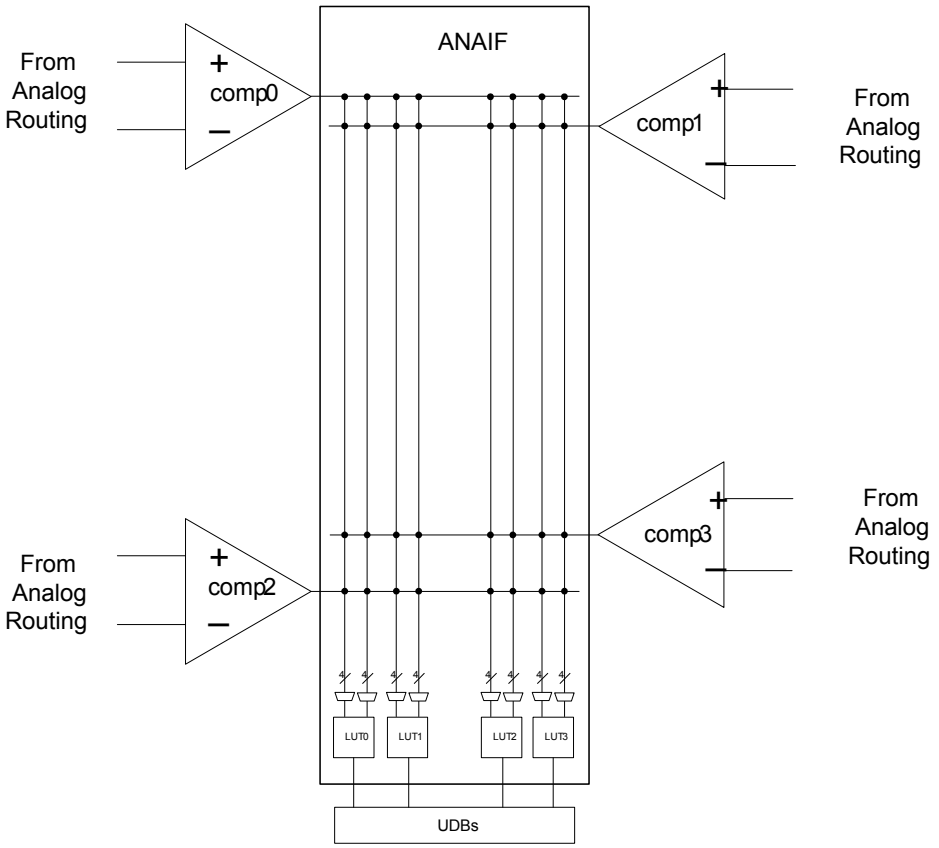
7.1.4.5 Nonintrusive Debugging

Figure 7-5. PSoC Creator Debugger



With SWD debug connectivity available on all devices, the PSoC Creator debugger offers full control over the target device with minimum intrusion. Breakpoints and code execution commands are all readily available from toolbar buttons and an impressive lineup of windows—register, locals, watch, call stack, memory and peripherals—make for an unparalleled level of visibility into the system.

Figure 8-4. Analog Comparator



8.3.2 LUT

The CY8C53 family of devices contains four LUTs. The LUT is a two input, one output lookup table that is driven by any one or two of the comparators in the chip. The output of any LUT is routed to the digital system interface of the UDB array. From the digital system interface of the UDB array, these signals can be connected to UDBs, DMA controller, I/O, or the interrupt controller.

The LUT control word written to a register sets the logic function on the output. The available LUT functions and the associated control word is shown in Table 8-1.

Table 8-1. LUT Function vs. Program Word and Inputs

Control Word	Output (A and B are LUT inputs)
0000b	**FALSE** (‘0’)
0001b	**A** AND **B**
0010b	**A** AND (NOT **B**)
0011b	A
0100b	(NOT **A**) AND **B**
0101b	B
0110b	**A** XOR **B**
0111b	**A** OR **B**
1000b	**A** NOR **B**
1001b	**A** XNOR **B**
1010b	NOT **B**
1011b	**A** OR (NOT **B**)
1100b	NOT **A**
1101b	(NOT **A**) OR **B**
1110b	**A** NAND **B**
1111b	**TRUE** (‘1’)

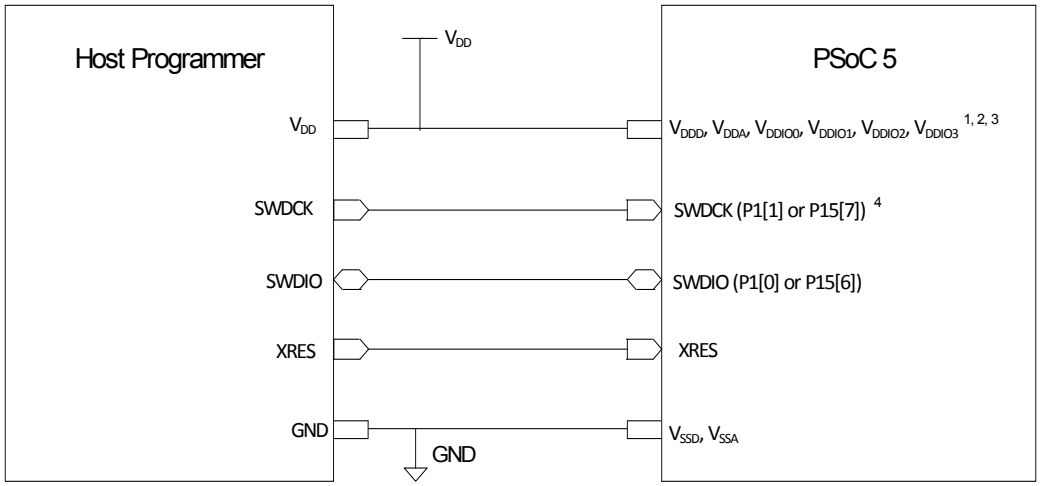
9.1 Debug Port Acquisition

Prior to programming or debugging, the debug port must be acquired. There is a time window after reset within which the Port Acquire must be completed. This window is initially 8 µs; if eight clocks are detected on the SWDCK line within the 8 µs period, the time window will then be extended to 400 µs to complete the port acquire operation. The port acquire key must be transmitted over one of the two SWD pin pairs; see SWD Interface. For a detailed description of the acquire key sequence, refer to the Technical Reference Manual

9.2 SWD Interface

SWD uses two pins, either two port 1 pins or the USBIO D+ and D- pins. The USBIO pins are useful for in system programming of USB solutions that would otherwise require a separate programming connector. One pin is used for the data clock (SWDCK) and the other is used for data input and output (SWDIO). SWD can be enabled on only one of the pin pairs at a time. When USB pins D+ and D- are used for SWD function, the SWDCK pin of port P1[1] is not available for use as a general purpose I/O and it should be externally pulled down using a resistor of less than 100 KΩ. SWD is used for debugging or for programming the flash memory. In addition, the SWD interface supports the SWV trace output. The SWD interface also includes the SWV interface, see SWV Interface on page 55. When using the SWD/SWV pins as standard GPIO, make sure that the GPIO functionality and PCB circuits do not interfere with SWD/SWV use. The SWV trace output is automatically activated whenever the SWD is activated.

Figure 9-1. SWD Interface Connections between PSoC 5 and Programmer



[1] The voltage levels of the Host Programmer and the PSoC 5 voltage domains involved in programming should be the same. XRES pin is powered by V_{DDIO1}. The USB SWD pins are powered by V_{DDD}. So for programming using the USB SWD pins with XRES pin, the V_{DDD}, V_{DDIO1} of PSoC 5 should be at the same voltage level as Host V_{DD}. Rest of PSoC 5 voltage domains (V_{DDA}, V_{DDIO0}, V_{DDIO2}, V_{DDIO3}) need not be at the same voltage level as host Programmer. The Port 1 SWD pins are powered by V_{DDIO1}. So V_{DDIO1} of PSoC 5 should be at same voltage level as host V_{DD} for Port 1 SWD programming. Rest of PSoC 5 voltage domains (V_{DDD}, V_{DDA}, V_{DDIO0}, V_{DDIO2}, V_{DDIO3}) need not be at the same voltage level as host Programmer.

[2] Vdda must be greater than or equal to all other power supplies (Vddd, Vddio's) in PSoC 5.

[3] For Power cycle mode Programming, XRES pin is not required. But the Host programmer must have the capability to toggle power (Vddd, Vdda, All Vddio's) to PSoC 5. This may typically require external interface circuitry to toggle power which will depend on the programming setup. The power supplies can be brought up in any sequence, however, once stable, VDDA must be greater than or equal to all other supplies.

[4] When USB SWD pins are used for Programming, the P1[1] SWDCK pin must be externally connected to Ground using external pull-down resistor (around 100 K resistor). This is required for P15[7] SWDCK signal to be seen by PSoC 5's internal logic.

11. Electrical Specifications

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 2.7 V to 5.5 V, except where noted. The unique flexibility of the PSoC UDBs and analog blocks enable many functions to be implemented in PSoC Creator components, see the component data sheets for full AC/DC specifications of individual functions. See the "Example Peripherals" section on page 32 for further explanation of PSoC Creator components.

11.1 Absolute Maximum Ratings

Table 11-1. Absolute Maximum Ratings DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
T_J	Operating die temperature		–55	–	110	°C
T_{STG}	Storage temperature	Recommended storage temperature is +25 °C ±25 °C. Extended duration storage temperatures above 85 °C degrade reliability.	–55	25	100	°C
V_{DDA}	Analog supply voltage relative to V_{SSA}		–0.5	–	6	V
V_{DDD}	Digital supply voltage relative to V_{SSD}		–0.5	–	6	V
V_{DDIO}	I/O supply voltage relative to V_{SSD}		–0.5	–	6	V
V_{CCA}	Direct analog core voltage input		–0.5	–	1.95	V
V_{CCD}	Direct digital core voltage input		–0.5	–	1.95	V
V_{SSA}	Analog ground voltage		V_{SSD} – 0.5	–	V_{SSD} + 0.5	V
V_{GPIO}[13]	DC input voltage on GPIO	Includes signals sourced by V_{DDA} and routed internal to the pin.	V_{SSD} – 0.5	–	V_{DDIO} + 0.5	V
V_{SIO}	DC input voltage on SIO	Output disabled	V_{SSD} – 0.5	–	7	V
		Output enabled	V_{SSD} – 0.5	–	6	V
I_{VDDIO}	Current per V_{DDIO} supply pin	Source	–	–	20	mA
		Sink	–	–	100	
LU	Latch up current[14]		–100	–	100	mA
ESD_{HBM}	Electrostatic discharge voltage	Human body model	500	–	–	V
ESD_{CDM}	ESD voltage	Charge device model	500	–	–	V

Note Usage above the absolute maximum conditions listed in Table 11-1 may cause permanent damage to the device. Exposure to maximum conditions for extended periods of time may affect device reliability. When used below maximum conditions but above normal operating conditions the device may not operate to specification.

Notes
13. The V_{DDIO} supply voltage must be greater than the maximum analog voltage on the associated GPIO pins. Maximum analog voltage on GPIO pin ≤ V_{DDIO} ≤ V_{DDA}.
14. Meets or exceeds JEDEC Spec EIA/JESD78 IC latch up test, at up to 85 °C.

Table 11-3. AC Specifications[19]

Parameter	Description	Conditions	Min	Typ	Max	Units
F_{CPU}	CPU frequency		DC	–	67.01	MHz
F_{BUSCLK}	Bus frequency		DC	–	67.01	MHz
Svdd	V_{DD} ramp rate		–	–	0.066	V/µs
$T_{STARTUP}$	Time from $V_{DDD}/V_{DDA}/V_{CCD}/V_{CCA}$ ≥ min operating voltage to CPU executing code at reset vector	No PLL used, IMO boot mode 12 MHz typ.	–	45	80	µs
T_{SLEEP}	Wakeup from sleep – CTW timeout to beginning of execution of next CPU instruction		–	125	–	µs
T_{SLEEP_INT}	Sleep timer periodic wakeup interval		–	–	128	ms

11.3 Power Regulators

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 2.7 V to 5.5 V, except where noted.

11.3.1 Digital Core Regulator

Table 11-4. Digital Core Regulator DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{DDD}	Input voltage		2.7	–	5.5	V
V_{CCD}	Output voltage		–	1.80	–	V
	Regulator output capacitor[21]	±10%, X5R ceramic or better. The two V_{CCD} pins must be shorted together, with as short a trace as possible, see Power System on page 22	–	1	10	µF

Figure 11-2. Regulators V_{CC} vs V_{DD}

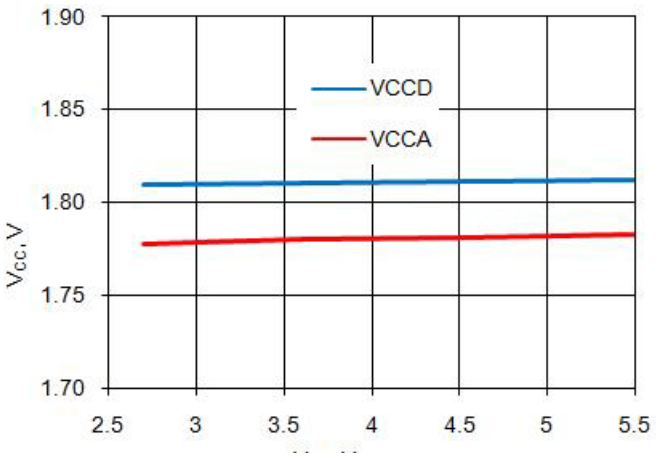
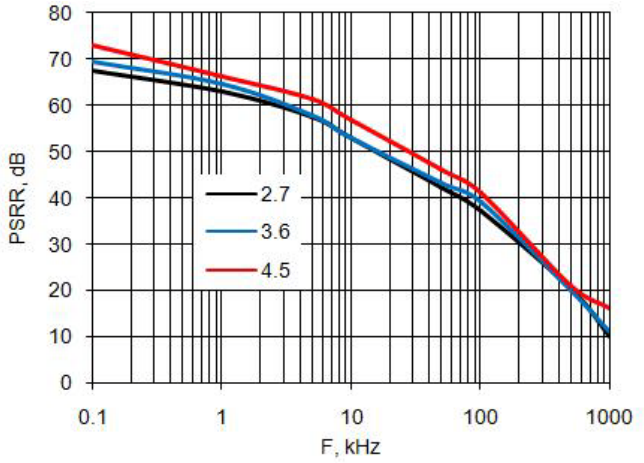


Figure 11-3. Digital Regulator PSRR vs Frequency and V_{DD}



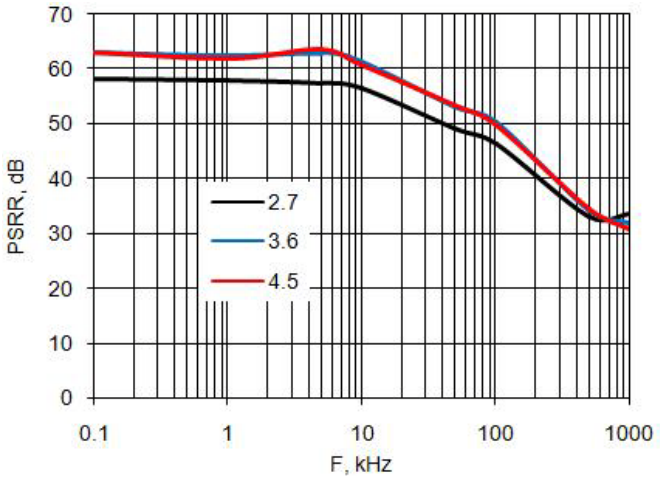
Note
21. 10 µF is required for sleep mode. See Table 11-3.

11.3.2 Analog Core Regulator

Table 11-5. Analog Core Regulator DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{DDA}	Input voltage		2.7	–	5.5	V
V_{CCA}	Output voltage		–	1.80	–	V
	Regulator output capacitor[24]	±10%, X5R ceramic or better	–	1	10	µF

Figure 11-4. Analog Regulator PSRR vs Frequency and V_{DD}



11.4 Inputs and Outputs

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 2.7 V to 5.5 V, except where noted. Unless otherwise specified, all charts and graphs show typical values.

11.4.1 GPIO

Table 11-6. GPIO DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{IH}	Input voltage high threshold	CMOS Input, PRT[x]CTL = 0	0.7 × V_{DDIO}	–	–	V
V_{IL}	Input voltage low threshold	CMOS Input, PRT[x]CTL = 0	–	–	0.3 × V_{DDIO}	V
V_{IH}	Input voltage high threshold	LVTTL Input, PRT[x]CTL = 1	2.0	–	–	V
V_{IL}	Input voltage low threshold	LVTTL Input, PRT[x]CTL = 1	–	–	0.8	V
V_{OH}	Output voltage high	I_{OH} = 4 mA at 3.3 V_{DDIO}	V_{DDIO} – 0.6	–	–	V
V_{OL}	Output voltage low	I_{OL} = 8 mA at 3.3 V_{DDIO}	–	–	0.6	V
Rpullup	Pull-up resistor		3.5	5.6	8.5	kΩ
Rpulldown	Pull-down resistor		3.5	5.6	8.5	kΩ
I_{IL}	Input leakage current (absolute value)[22]	25 °C, V_{DDIO} = 3.0 V	–	–	2	nA

Notes
22. Based on device characterization (Not production tested).
23. For information on designing with PSoC 3 oscillators, refer to the application note, AN54439 - PSoC® 3 and PSoC 5 External Oscillator.
24. 10 µF is required for sleep mode. See Table 11-3.

Figure 11-7. GPIO Output Rise and Fall Times, Fast Strong Mode, V_{DDIO} = 3.3 V, 25 pF Load

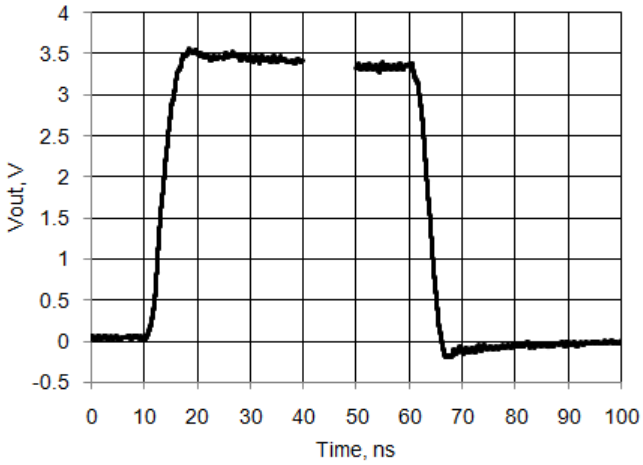
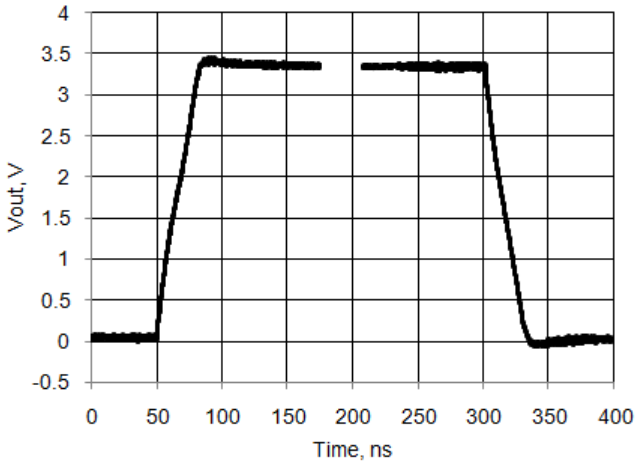


Figure 11-8. GPIO Output Rise and Fall Times, Slow Strong Mode, V_{DDIO} = 3.3 V, 25 pF Load



11.4.2 SIO

Note that under certain conditions an SIO pin may cause up to 1 mA of additional current to be drawn from the related V_{DDIO} pin. If an SIO pin's voltage exceeds its V_{DDIO} supply by 0.5 V, the trigger condition is set. After the trigger condition is set, the SIO pin causes increased current when its voltage is between V_{SSD} + 0.5 V and V_{DDIO} – 0.5 V. The trigger condition is reset when the SIO pin is brought within the range of V_{SSD} to V_{SSD} + 0.5 V. The trigger condition may unknowningly be met during device powerup due to differences in supply ramps.

Table 11-8. SIO DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Vinmax	Maximum input voltage	All allowed values of Vddio and Vddd, see *Section 11.2.1*	–	–	5.5	V
Vinref	Input voltage reference (Differential input mode)		0.5	–	0.52 × V_{DDIO}	V
Voutref	Output voltage reference (Regulated output mode)					
		V_{DDIO} > 3.7	1	–	V_{DDIO} – 1	V
		V_{DDIO} < 3.7	1	–	V_{DDIO} – 0.5	V
V_{IH}	Input voltage high threshold					
	GPIO mode	CMOS input	0.7 × V_{DDIO}	–	–	V
	Differential input mode[26]	Hysteresis disabled	SIO_ref + 0.2	–	–	V
V_{IL}	Input voltage low threshold					
	GPIO mode	CMOS input	–	–	0.3 × V_{DDIO}	V
	Differential input mode[26]	Hysteresis disabled	–	–	SIO_ref – 0.2	V
V_{OH}	Output voltage high					
	Unregulated mode	I_{OH} = 4 mA, V_{DDIO} = 3.3 V	V_{DDIO} – 0.4	–	–	V
	Regulated mode[26]	I_{OH} = 1 mA	SIO_ref – 0.65	–	Voutref + 0.2	V
	Regulated mode[26]	I_{OH} = 0.1 mA	SIO_ref – 0.3	–	SIO_ref + 0.2	V
V_{OL}	Output voltage low	V_{DDIO} = 3.30 V, I_{OL} = 25 mA	–	–	0.8	V
Rpullup	Pull-up resistor		3.5	5.6	8.5	kΩ
Rpulldown	Pull-down resistor		3.5	5.6	8.5	kΩ
I_{IL}	Input leakage current (absolute value)[27]					
	V_{IH} ≤ Vddsio	25 °C, Vddsio = 3.0 V, V_{IH} = 3.0 V	–	–	14	nA
	V_{IH} > Vddsio	25 °C, Vddsio = 0 V, V_{IH} = 3.0 V	–	–	10	µA

Notes
26. See Figure 6-8 on page 28 and Figure 6-11 on page 31 for more information on SIO reference.
27. Based on device characterization (Not production tested).

Table 11-12. USB Driver AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
Tr	Transition rise time		–	–	20	ns
Tf	Transition fall time		–	–	20	ns
TR	Rise/fall time matching	V_{USB_5}, $V_{USB\_3.3}$, see USB DC Specifications on page 87	80%	–	135%	
Vcrs	Output signal crossover voltage		1.1	–	2.3	V

11.4.4 XRES

Table 11-13. XRES DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{IH}	Input voltage high threshold		0.7 × V_{DDIO}	–	–	V
V_{IL}	Input voltage low threshold		–	–	0.3 × V_{DDIO}	V
Rpullup	Pull-up resistor		3.5	5.6	8.5	kΩ
C_{IN}	Input capacitance[31]		–	3	–	pF
V_H	Input voltage hysteresis (Schmitt-Trigger)[31]		–	100	–	mV
Idiode	Current through protection diode to V_{DDIO} and V_{SSIO}		–	–	100	µA

Table 11-14. XRES AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
T_{RESET}	Reset pulse width		1	–	–	µs

11.5 Analog Peripherals

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Specifications are valid for 2.7 V to 5.5 V, except where noted.

11.5.1 Opamp

Table 11-15. Opamp DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_I	Input voltage range		V_{SSA}	–	V_{DDA}	V
V_{OS}	Input offset voltage	Operating temperature > 70 °C	–	–	3	mV
		Operating temperature –40 °C to 70 °C	–	–	2	mV
TCV_{OS}	Input offset voltage drift with temperature		–	–	±30	µV / °C
Ge1	Gain error, unity gain buffer mode	Rload = 1 kΩ	–	–	±0.1	%
C_{IN}	Input capacitance	Routing from pin	–	–	18	pF
Vo	Output voltage range	1 mA, source or sink	V_{SSA} + 0.05	–	V_{DDA} – 0.05	V
I_{OUT}	Output current, source or sink	V_{SSA} + 500 mV ≤ Vout ≤ V_{DDA} –500 mV	10	–	–	mA
I_{DD}	Quiescent current	Vssa + 50 mV < V_{IN} < V_{DDA}-50 mV	–	1	2.5	mA
CMRR	Common mode rejection ratio		80	–	–	dB
PSRR	Power supply rejection ratio		75	–	–	dB

Note
31. Based on device characterization (Not production tested).

Table 11-16. Opamp AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
GBW	Gain-bandwidth product	200 pF load	3	–	–	MHz
SR	Slew rate, 20% - 80%	200 pF load	3	–	–	V/µs
e_n	Input noise density	Vdda = 5 V, at 100 kHz	–	45	–	nV/sqrtHz

Figure 11-21. Opamp Step Response, Rising

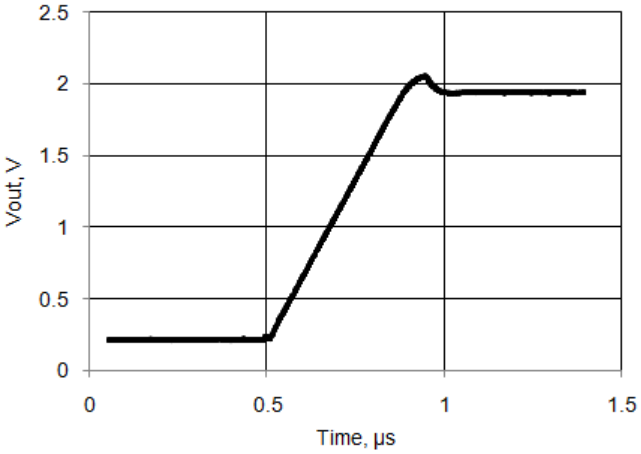


Figure 11-23. Opamp Step Response, Falling

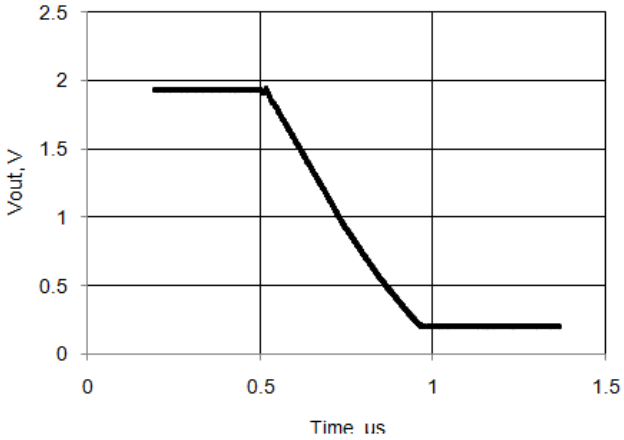
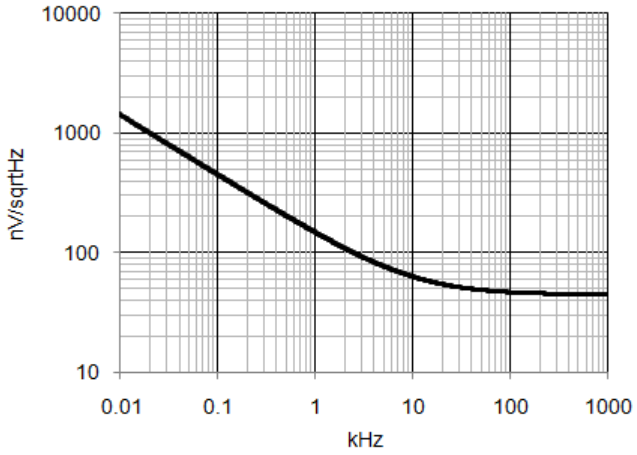


Figure 11-22. Opamp Noise vs Frequency, V_{DDA} = 5V



11.5.2 Voltage Reference

Table 11-17. Voltage Reference Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
V_{REF}	Precision reference voltage	Initial trimming	1.017 (–0.7%)	1.024	1.033 (+0.9%)	V
	Temperature drift[32]		–	–	57	ppm/°C
	Long term drift		–	100	–	ppm/Khr
	Thermal cycling drift (stability)[32]		–	100	–	ppm

Note
32. Based on device characterization (Not production tested).

11.5.3 SAR ADC

Unless otherwise specified, operating conditions are:

- Operation in continuous sample mode
- Fclk = 14 MHz
- Input range = ± V_{REF}
- Bypass capacitor of 10 µF

Table 11-18. SAR ADC DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Resolution		–	–	12	bits
	Number of channels – single-ended		–	–	No of GPIO	
	Number of channels – differential	Differential pair is formed using a pair of neighboring GPIO.	–	–	No of GPIO/2	
	Monotonicity[33]		Yes	–	–	
Ge	Gain error	External reference	–	–	±0.2	%
V_{OS}	Input offset voltage	V_{CM} = 0 V	–	–	±2	mV
		V_{CM} = $V_{DD/2}$			±6	
I_{DD}	Current consumption		–	–	1	mA
	Input voltage range – single-ended[33]		V_{SSA}	–	V_{DDA}	V
	Input voltage range – differential[33]		V_{SSA}	–	V_{DDA}	V
PSRR	Power supply rejection ratio[33]		70	–	–	dB
CMRR	Common mode rejection ratio		35	–	–	dB
INL	Integral non linearity[33]	Internal reference from V_{BG}	–	–	±2	LSB
DNL	Differential non linearity[33]	Internal reference from V_{BG}	–	–	±2	LSB

Figure 11-24. SAR ADC DNL vs Output Code, Bypassed Internal Reference Mode

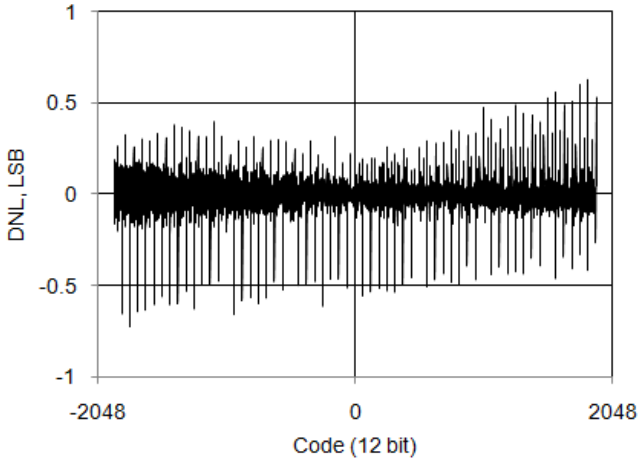
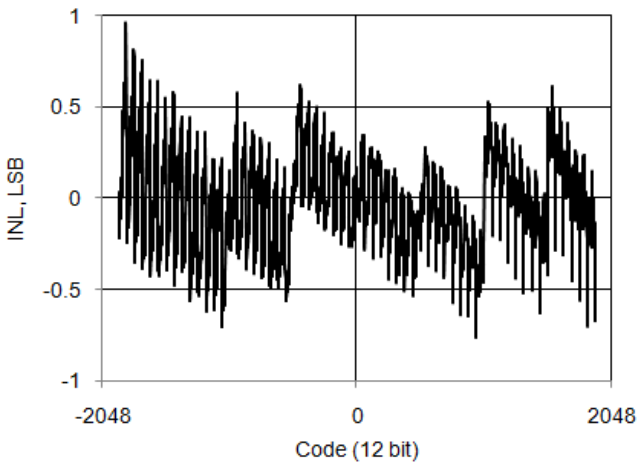


Figure 11-25. SAR ADC INL vs Output Code, Bypassed Internal Reference Mode



11.5.7 Voltage Digital to Analog Converter (VDAC)

See the VDAC component datasheet in PSoC Creator for full electrical specifications and APIs.

Unless otherwise specified, all charts and graphs show typical values.

Table 11-25. VDAC DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
	Resolution		–	8	–	bits
INL1	Integral nonlinearity	1 V scale	–	±2.1	±2.5	LSB
DNL1	Differential nonlinearity	1 V scale	–	±0.3	±1	LSB
Rout	Output resistance	1 V scale	–	4	–	kΩ
		4 V scale	–	16	–	kΩ
V_{OUT}	Output voltage range, code = 255	1 V scale	–	1.02	–	V
		4 V scale, Vdda = 5 V	–	4.08	–	V
	Monotonicity		–	–	Yes	–
V_{OS}	Zero scale error		–	0	±0.9	LSB
Eg	Gain error	1 V scale	–	–	±5	%
		4 V scale	–	–	±5	%
TC_Eg	Temperature coefficient, gain error	1 V scale	–	–	0.03	%FSR / °C
		4 V scale	–	–	0.03	%FSR / °C
I_{DD}	Operating current	4 V slow mode	–	–	100	µA
		4 V fast mode	–	–	500	µA
		1 V slow mode	–	–	300	µA
		1 V fast mode	–	–	600	µA

Figure 11-44. VDAC INL vs Input Code, 1 V Mode

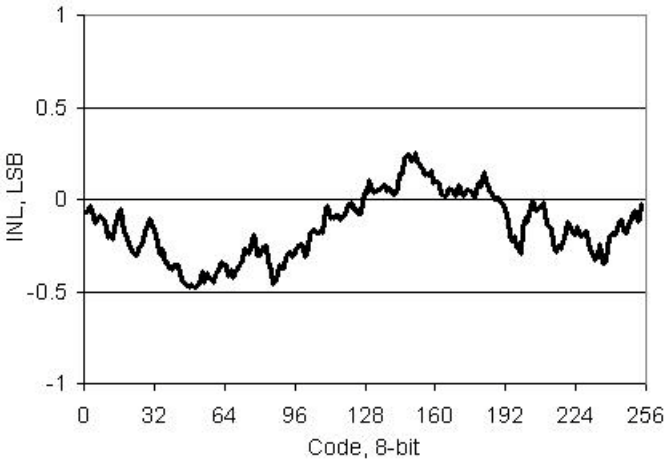


Figure 11-45. VDAC DNL vs Input Code, 1 V Mode

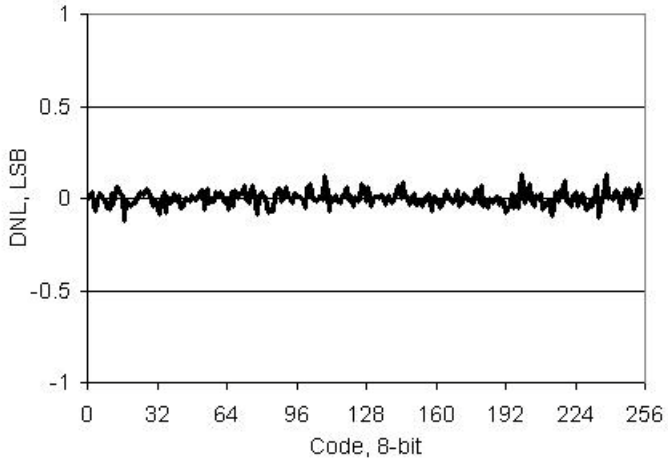


Figure 11-56. Bandwidth vs. Temperature, Gain = 1, Power Mode = High

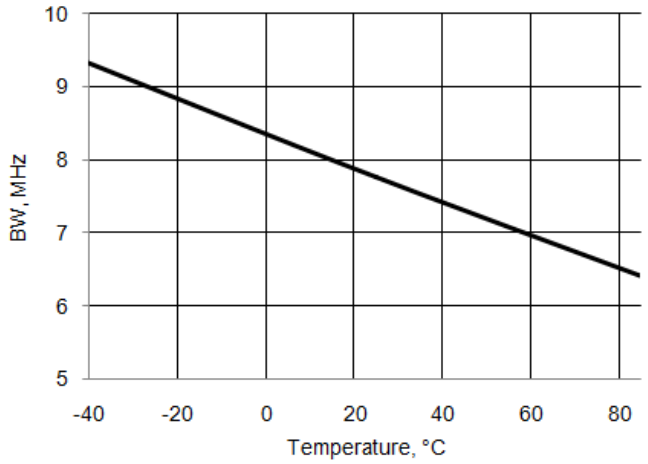
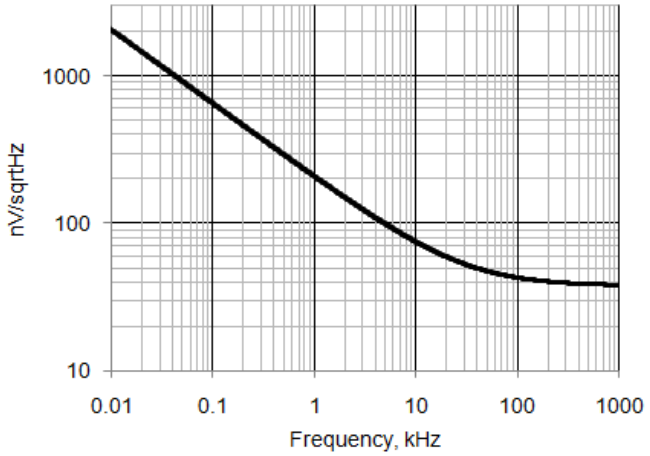


Figure 11-57. Noise vs. Frequency, V_{DDA} = 5 V, Power Mode = High



11.5.11 LCD Direct Drive

Table 11-33. LCD Direct Drive DC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
I_{CC}	LCD system operating current	Bus clock = 3 MHz, Vddio = Vdda = 3 V, 4 commons, 16 segments, 1/4 duty cycle, 50 Hz frame rate, no glass connected	–	63	–	µA
I_{CC_SEG}	Current per segment driver		–	148	–	µA
V_{BIAS}	LCD bias range (V_{BIAS} refers to the main output voltage(V0) of LCD DAC)	3 V ≤ V_{BIAS} ≤ V_{DDIO} for the drive pin	2.09	–	5.2	V
	LCD bias step size	3 V ≤ V_{BIAS} ≤ V_{DDIO} for the drive pin	–	25.8	–	mV
	LCD capacitance per segment/common driver	Drivers may be combined	–	500	5000	pF
	Long term segment offset	V_{BIAS} ≤ V_{DDA} – 0.5 V	–	–	20	mV
I_{OUT}	Output drive current per segment driver)	Vddio = 5.5V	90	–	165	µA

Table 11-34. LCD Direct Drive AC Specifications

Parameter	Description	Conditions	Min	Typ	Max	Units
f_{LCD}	LCD frame rate		10	50	150	Hz

13. Packaging

Table 13-1. Package Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Units
T_A	Operating ambient temperature		–40	25	85	°C
T_J	Operating junction temperature		–40	–	100	°C
Tja	Package θ_{JA} (68-pin QFN)		–	15	–	°C/Watt
Tja	Package θ_{JA} (100-pin TQFP)		–	34	–	°C/Watt
Tjc	Package θ_{JC} (68-pin QFN)		–	13	–	°C/Watt
Tjc	Package θ_{JC} (100-pin TQFP)		–	10	–	°C/Watt

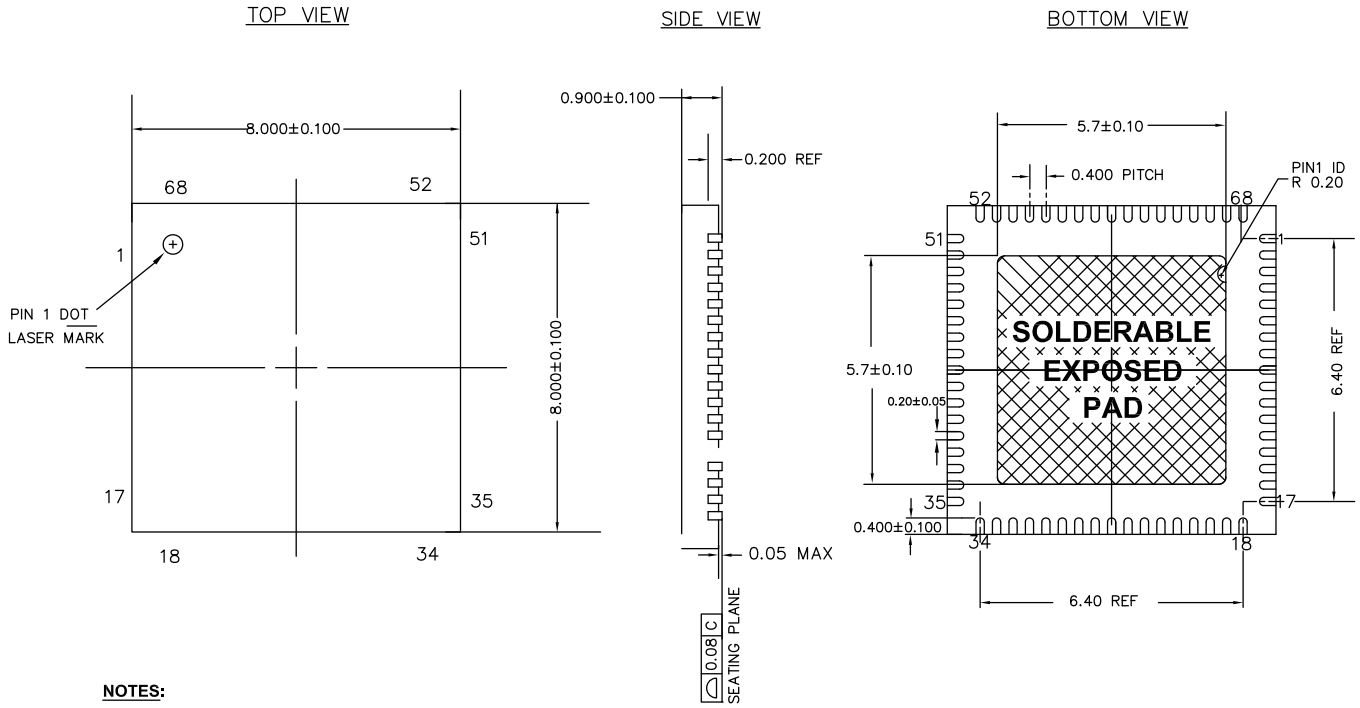
Table 13-2. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
68-pin QFN	260 °C	30 seconds
100-pin TQFP	260 °C	30 seconds

Table 13-3. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2

Package	MSL
68-pin QFN	MSL 3
100-pin TQFP	MSL 3

Figure 13-1. 68-Pin QFN 8x8 with 0.4 mm Pitch Package Outline (Sawn Version)



NOTES:
1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: 0.17g
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-09618 *D

16. Document Conventions

16.1 Units of Measure

Table 16-1. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibels
fF	femtofarads
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohours
kHz	kilohertz
kΩ	kilohms
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	megaohms
Msps	megasamples per second
µA	microamperes
µF	microfarads
µH	microhenrys
µs	microseconds
µV	microvolts
µW	microwatts
mA	milliamperes
ms	milliseconds
mV	millivolts
nA	nanoamperes
ns	nanoseconds
nV	nanovolts
Ω	ohms
pF	picofarads
ppm	parts per million
ps	picoseconds
s	seconds
sps	samples per second
sqrtHz	square root of hertz
V	volts